

APPLICATION NOTE

Document NO. AN-GEN-001

Date : 23th Dec. 1998

Prepared :K.Kajiwara

Confirmed :T.Ohkawa

SUBJECT: Characteristics for Thermal Silicon Compound "ShinEtsu G746".

INTRODUCTION:

When the RF module is mounted onto a heat sink of a equipment, thermal compound to get heat sinking should be applied between the modules fin and the heat sink. Following thermal compound is recommended.

G746 ShinEtsu Chemical Industry Co., Ltd.

ADVANTAGE:

1. "ShinEtsu G746" has excelent thermal conductivity and which is 3 times improved compare to previous type.
2. "ShinEtsu G746" has wide range of usable temperature.

GENERAL CHARACTERISTICS:

1. Weight ratio: 2.66 @25deg.C
2. Thermal conductivity: 1.6x10E-3 (cal/cm-sec-deg.C)
3. Resistance : 1.2x10E14 (ohm-cm)
4. Temperature range: -50 to +150deg.C

(Above parameters will be subject to change by ShinEtsu Chemical Industry Co., Ltd.)

PRECAUTIONS:

Concerning to handling and strage "ShinEtsu G746" and details of characteristics, please contuct to ShinEtsu Chemical Industry Co., Ltd. (Japan)